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PTO/SB/01 (10-00)

Approved for use through 10/31/2002. OMB 0651-0032

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**DECLARATION FOR UTILITY OR  
DESIGN  
PATENT APPLICATION  
(37 CFR 1.63)  
WITH POWER OF ATTORNEY**

☒ Declaration Submitted with Initial Filing **OR** ☐ Declaration Submitted after Initial Filing (surcharge (37 CFR 1.16 (e)) required)

Attorney Docket Number 4231/PCT  
First Named Inventor Helmut HEINZ

**COMPLETE IF KNOWN**

Application Number /  
Filing Date September 4, 2001  
Group Art Unit  
Examiner Name

As a below named inventor, I hereby declare that:

My residence, mailing address, and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR PRODUCING CIRCUIT ARRANGEMENTS

(Title of the Invention)

the specification of which

☐ is attached hereto  
OR

☒ was filed on (MM/DD/YYYY) 01. March 2000 as United States Application Number or PCT International Application Number PCT/EP00/01770 and was amended on (MM/DD/YYYY) (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or any PCT international application having a filing date before that of the application on which priority is claimed.

Priority Foreign Application Number(s)	Country	Foreign Filing Date (MM/DD/YYYY)	Priority Not Claimed	Certified Copy Attached?	
				YES	NO
199 09 505.1	Federal Republic of Germany	03/04/99	<input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>	<input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>	<input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>

☐ Additional foreign application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto:

I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below.

Application Number(s)	Filing Date (MM/DD/YYYY)	<input type="checkbox"/> Additional provisional application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

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# DECLARATION

ADDITIONAL INVENTOR(S)  
Supplemental Sheet  
Page 2 of 2

Name of Additional Joint Inventor, if any:

☐ A petition has been filed for this unsigned inventor

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Inventor's Signature

Date

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Mailing Address

City

State

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Country

ATTORNEY DOCKET NO. 4231/PCT

DOCKET NO.: 4231/PCT  
INVENTOR: Helmut HEINZ et al.

TRANSLATOR'S DECLARATION

I Wolfgang G. Fasse, having an office at 58-G Main Road North,  
(translator's name) (translator's office address)  
Hampden, Maine 04444-0726, U.S.A.

and a mailing address: Fasse Patent Attorneys, P. A.,  
(translator's mailing address)  
P.O. Box 726, Hampden, Maine 04444-0726, U.S.A.

solemnly declare:

that I am fully conversant and knowledgeable in the German language to fluently read, write, and speak it, I am also fully conversant and knowledgeable in the English language;

that I have, to the best of my ability, prepared the attached accurate, complete and literal translation of Amended PCT claims 1 to 5 of:

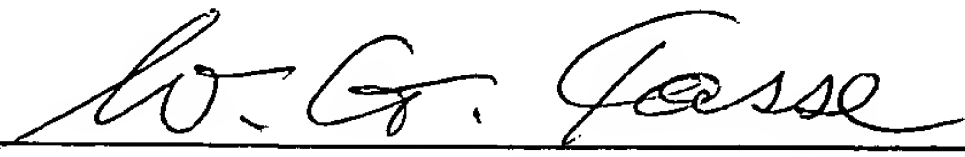
International PCT Application No. PCT/EP00/01770

International Application Filed: March 1, 2000.

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: September 4, 2001

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(translator's signature)  
Name: Wolfgang G. Fasse  
(translator's name)

LITERAL AND VERIFIED TRANSLATION OF AMENDED PCT CLAIMS 1 TO 5

1 1. Method for producing of circuit arrangements, the  
2 components of which are attached to the top surface (12) of  
3 a carrier body (5) having thermal lead-through contacts  
4 (7), wherein, prior to the soldering operation, the thermal  
5 lead-through contacts (7) are closed from the underside  
6 (13) of the carrier body (5) with screen printing material  
7 (8) by a screen printing process, and wherein a first  
8 metallizing layer (6) forming the base metallization, is  
9 applied on the carrier body (5) and in the thermal lead-  
10 through contacts (7), characterized in that a highly  
11 viscous screen printing material (8) is printed on the  
12 metallizing layer (6) forming the base metallization, that,  
13 following the curing of the screen printing material (8),  
14 remainders of the screen printing material (8) protruding  
15 from the underside of the carrier body (5) are removed by  
16 at least one mechanical cleaning process and/or by a  
17 chemical cleaning process, and that, following said at  
18 least one cleaning process, at least one further  
19 metallizing layer (17) forming the finished metallization  
20 is applied onto the metallizing layer (6) forming the base  
21 metallization.

1 2. The method of claim 1, characterized in that mechanical  
2 brush grinding is used as said mechanical cleaning  
3 operation.

1     **3:**     The method of claim 1 or 2, characterized in that following  
2             the application of the metallization layer (17) forming the  
3             final metallization, the components of the circuit  
4             arrangement are attached to the top surface (12) of the  
5             carrier body (5) by a reflow soldering process.

1     **4.**     The method of one of claims 1 to 3, characterized in that  
2             a thermally conducting, electrically insulating film (9) is  
3             applied to the underside (13) of the carrier body (5).

1     **5.**     Method of claims 1 to 4, characterized in that said  
2             thermally conducting, electrically insulating film (9) is  
3             connected to a cooling body (10).